ON Semiconductor



INITIAL PRODUCT/PROCESS CHANGE NOTIFICATION Generic Copy

24-Aug-2005

SUBJECT: ON Semiconductor Initial Product/Process Change Notification #15005

TITLE: Initial Notification - Qualification of the MAX809 MAX810 NCP803 on the ACMOS2 Technology

EFFECTIVE DATE: 24-Oct-2005

AFFECTED CHANGE CATEGORY: Wafer Process

AFFECTED PRODUCT DIVISION: Analog Power Management

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION: Contact Sales Office or Christelle Gioia < r43164 @onsemi.com>

NOTIFICATION TYPE:

Initial Product/Process Change Notification (IPCN)

First change notification sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.

The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN).

This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 60 days prior to implementation of the change.

DESCRIPTION AND PURPOSE:

This is the Initial Product Change Notification announcing the qualification and redesign of the MAX809, MAX810, and NCP803 on the previously qualified ACMOS2 technology process at ON Semiconductors MOS7A facility.

Die fabrication will continue at the current wafer fab site, ON Semiconductor MOS7A, in Aizu, Japan.

Device performance and reliability will continue to meet or exceed ON Semiconductor standards.

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QUALIFICATION PLAN:

ACMOS2 technology was previously qualified. These devices will be qualified with 1 lot: HTOL High Temp Op Life for 168 hrs. Tj =150°C, 80 units/lot, TC -40°C to +125°C for 500 cycles, 80 units /lot, UHAST 130°C/85% RH for 96 hrs, 80 units/lot, ESD (MM,HBM), and U-Dynamic Latchup Electrical Temperature characterization will also be completed.

AFFECTED DEVICE LIST:

PART

MAX809SN160T1 MAX809SN160T1G MAX809SN232T1 MAX809SN232T1G MAX809SN490T1 MAX809SN490T1G MAX809RTR MAX809RTRG MAX809STR MAX809STRG MAX809TTR MAX809TTRG MAX809JTR MAX809JTRG MAX809MTR MAX809MTRG MAX809HTR MAX809HTRG MAX809LTR MAX809LTRG MAX810RTR MAX810RTRG MAX810STR MAX810STRG MAX810TTR MAX810TTRG MAX810MTR MAX810MTRG MAX810LTR MAX810LTRG NCP803SN160T1 NCP803SN160T1G NCP803SN232T1 NCP803SN232T1G NCP803SN263T1 Initial Product/Process Change Notification #15005

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NCP803SN263T1G NCP803SN293T1 NCP803SN293T1G NCP803SN293T3 NCP803SN293T3G NCP803SN308T1 NCP803SN308T1G NCP803SN438T1 NCP803SN438T1G NCP803SN463T1 NCP803SN463T1G